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Enable High Flux and Cost Efficient System

Z Power Chip on board – ZC series SDW*5F1C (SDW05F1C, SDW85F1C, SDW95F1C)









Product Brief

Description

- The ZC series are LED arrays which provide High Flux and High Efficacy.
- It is especially designed for easy assembly of lighting fixtures by eliminating reflow soldering process.
- It's thermal management is better than other power LED solutions with wide Metal area.
- ZC series are ideal light sources for General Lighting applications including Replacement Lamps, Industrial & Commercial Lightings and other high Lumen required applications.

Features and Benefits

- Size 28mm * 28mm
- Power dissipation 35.8 ~ 74W
- Wide CCT range with CRI70~90
- Forward V_F typ 35.8V
- Maximum Current 1.84A
- MacAdam 3-step binning
- Uniformed Shadow
- · Excellent Thermal management
- RoHS compliant

Key Applications

- Commercial Downlight
- Industrial High/Low Bay lighting
- Residential
- Replacement lamps Bulb, PAR
- Outdoor area Street lighting, Tunnel lighting, Parking area lighting

Table 1. Product Selection Table

Part Number	сст [к]							
rait Nullibel	Color	Min.	Тур.	Max.				
SDW05F1C	Cool White	4,700	-	6,000				
SDWOSFIC	Neutral White	3,700	-	4,700				
	Cool White	4,700	-	6,000				
SDW85F1C	Neutral White	3,700	-	4,700				
	Warm White	2,600	-	3,700				
SDW95F1C	Neutral White	3,700	-	4,200				
3DW93F1C	Warm White	2,600	-	3,700				



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Product Performance & Characterization Guide

Table 2. Electro Optical Characteristics, T_i=25°C

Part Number	CCT (K) ^[1]	Typical Luminous Flux ^[2] , Φ _V ^[3] (lm)		Typical Forw V _F ^{[4}	vard Voltage,	CRI ^[5] , R _a	Viewing Angle (degrees) 20 ½
	Тур.	1A	1.84A*	1A	1.84A*	Min.	Тур.
	5600	5200	8216	35.8	37.5	70	120
CDW05E4C	5000	5300	8374	35.8	37.5	70	120
SDW05F1C	4500	5200	8216	35.8	37.5	70	120
	4000	5180	8184	35.8	37.5	70	120
	5600	4878	7512	35.8	37.5	80	120
	5000	4961	7639	35.8	37.5	80	120
SDW85F1C	4000	4783	7356	35.8	37.5	80	120
3DW65FTC	3500	4680	7198	35.8	37.5	80	120
	3000	4575	7036	35.8	37.5	80	120
	2700	4400	6767	35.8	37.5	80	120
	4000	4100	5207	35.8	37.5	90	120
SDW95F1C	3500	3876	4923	35.8	37.5	90	120
2DW32F1C	3000	3800	4826	35.8	37.5	90	120
	2700	3700	4699	35.8	37.5	90	120

Notes:

- (1) Correlated Color Temperature is derived from the CIE 1931 Chromaticity diagram. Color coordinate: ± 0.01 , CCT $\pm 5\%$ tolerance.
- (2) Seoul Semiconductor maintains a tolerance of $\pm 7\%$ on flux and power measurements.
- (3) Φ_V is the total luminous flux output as measured with an integrating sphere.
- (4) Tolerance is $\pm 3\%$ on forward voltage measurements.
- (5) Tolerance is ± 2 on CRI measurements.

^{*} No values are provided by real measurement. Only for reference purpose.

Product Performance & Characterization Guide

Table 3. Electro Optical Characteristics, T_i=85°C

Part Number	CCT (K) [1]	Typical Luminous Flux $^{[2]}$, $\Phi_{V}^{[3]}$ (lm)	Typical Forward Voltage, V _F ^[4] (V)	
	Тур.	1A*	1A*	
	5600	4680	34.3	
SDW05F1C	5000	4770	34.3	
SDWOSFIC	4500	4680	34.3	
	4000	4662	34.3	
	5600	4341	34.3	
	5000	4415	34.3	
SDW85F1C	4000	4257	34.3	
SDWOSFIG	3500	4165	34.3	
	3000	4072	34.3	
	2700	3916	34.3	
	4000	3567	34.3	
SDW95F1C	3500	3372	34.3	
2DM32LIC	3000	3306	34.3	
	2700	3219	34.3	

Notes:

- (1) Correlated Color Temperature is derived from the CIE 1931 Chromaticity diagram. Color coordinate : ± 0.01 , CCT $\pm 5\%$ tolerance.
- (2) Seoul Semiconductor maintains a tolerance of $\pm 7\%$ on flux and power measurements.
- (3) Φ_V is the total luminous flux output as measured with an integrating sphere.
- (4) Tolerance is $\pm 3\%$ on forward voltage measurements.
- (5) Tolerance is ± 2 on CRI measurements.

^{*} No values are provided by real measurement. Only for reference purpose.

Product Performance & Characterization Guide

Table 4. Absolute Maximum Characteristics, $T_j=25^{\circ}C$

Davamatav	Cymhal		Unit		
Parameter	Symbol	Min.	Тур.	Max.	Unit
Forward Current	l _F	-	1	1.84	Α
Power Dissipation	P_d	-	35.8	74	W
Junction Temperature	T _j	-	-	140	ōC
Operating Temperature	T_{opr}	-40	-	85	ōC
Surface Temperature	T _S	-	-	100	ōC
Storage Temperature	T_{stg}	-40	-	100	ōC
Thermal resistance (J to S) [1]	Rθ _{J-S}	-	0.48	-	K/W
ESD Sensitivity(HBM)	-		Class 3A JE	SD22-A114-E	

Notes:

(1) Thermal Resistance : $R\theta_{J\text{-}S}$ (Junction to Ts point)

Fig 1. Color Spectrum, T_i=25 ℃, I_F=1A (CRI70)

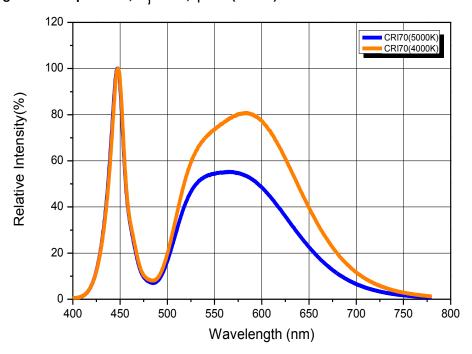


Fig 2. Color Spectrum, T_i=25 ℃, I_F=1A (CRI80)

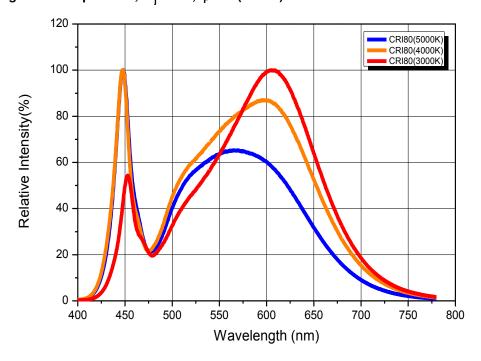


Fig 3. Color Spectrum, $T_i=25\,^{\circ}$ C, $I_F=1A$ (CRI90)

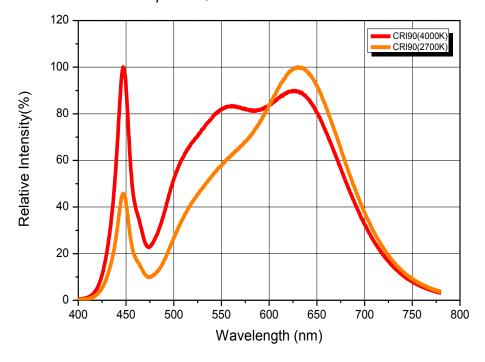


Fig 4. Radiant pattern, T_i=25 ℃, I_F=1A

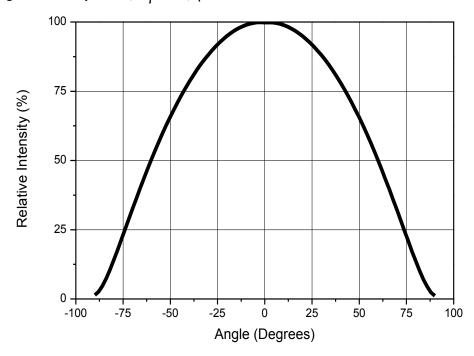


Fig 5. Forward Voltage vs. Forward Current, $T_i=25$ $^{\circ}$ C

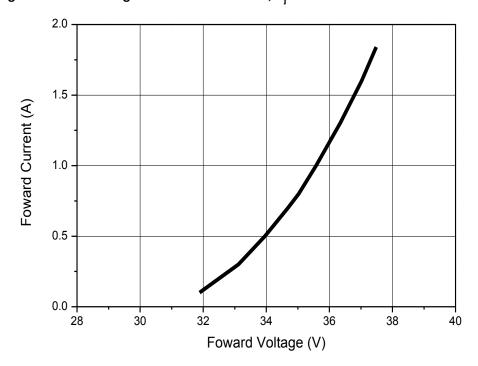


Fig 6. Forward Current vs. Relative Luminous Flux, T_i =25 $^{\circ}$ C

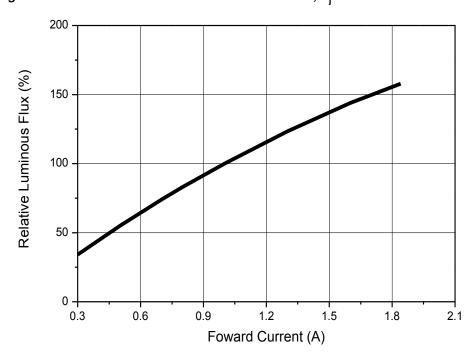


Fig 7. Junction Temperature vs. Relative Light Output, I_F=1A

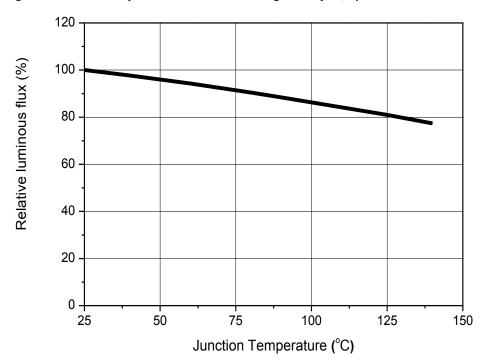


Fig 8. Junction Temperature vs. Forward Voltage, I_F=1A

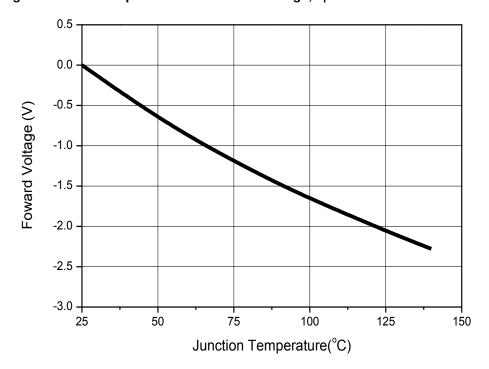


Fig 9. Junction Temperature vs. CIE X, Y Shift, I_F=1A (CRI70)

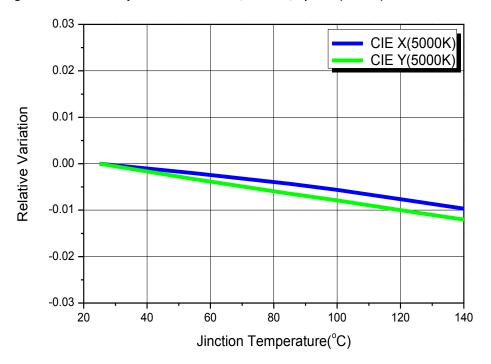


Fig 10. Junction Temperature vs. CIE X, Y Shift, $I_F=1A$ (CRI90)

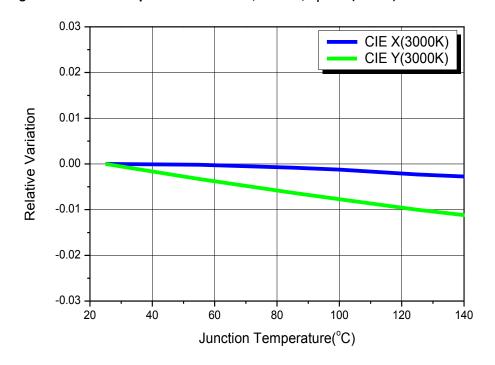
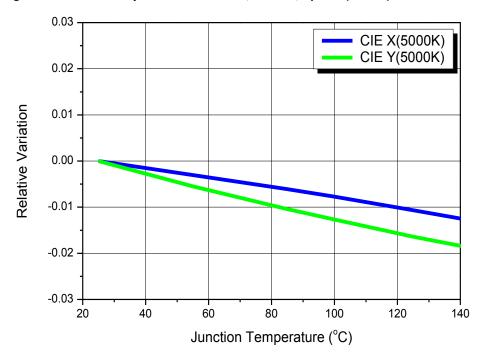


Fig 11. Junction Temperature vs. CIE X, Y Shift, I_F=1A (CRI80)



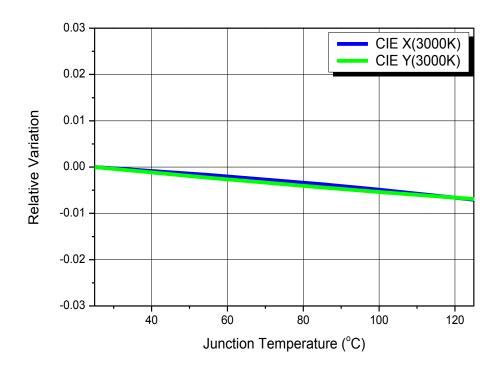
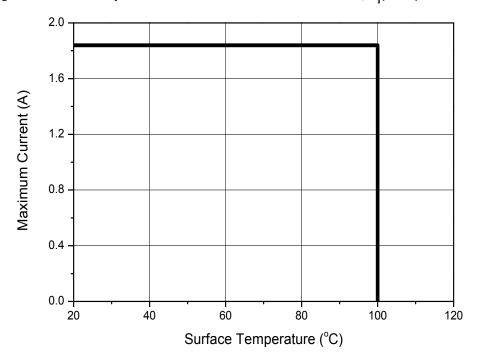


Fig 12. Surface Temperature vs. Maximum Forward Current, T_i(max.)=140 ℃



Product Nomenclature

Table 5. Part Numbering System : $X_1X_2X_3X_4X_5X_6X_7X_8$

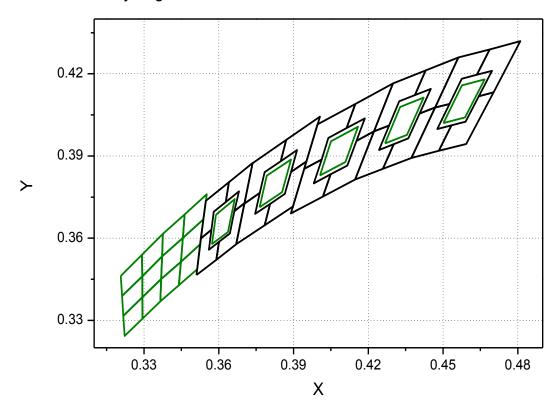
Part Number Code	Description	Part Number	Value
X ₁	Company	S	
X ₂	Package series	D	
X ₃ X ₄	Color Specification	W0	CRI 70
		W8	CRI 80
		W9	CRI 90
X ₅	Series number	5	
X ₆	Lens type	F	Flat
X ₇	PCB type	1	PCB
X ₈	Revision number	С	New COB type

Table 6. Lot Numbering System : $Y_1Y_2Y_3Y_4Y_5Y_6 - Y_7Y_8Y_9Y_{10} - Y_{11}Y_{12}Y_{13}$

Lot Number Code	Description
Y ₁ Y ₂	Year
Y ₃ Y ₄	Month
Y ₅ Y ₆	Day
Y ₇ Y ₈ Y ₉ Y ₁₀	Mass order
Y ₁₁ Y ₁₂ Y ₁₃	Tray No.

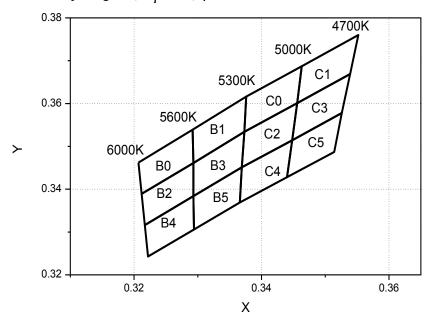
Color Bin Structure

CIE Chromaticity Diagram



Color Bin Structure

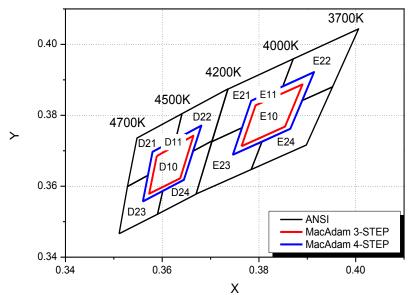
CIE Chromaticity Diagram, $T_i=25\,^{\circ}$ C, $I_F=1A$



	B0	В	1	В	2
CIE x	CIE y	CIE x	CIE y	CIE x	CIE y
0.3207	0.3462	0.3292	0.3539	0.3212	0.3389
0.3212	0.3389	0.3293	0.3461	0.3217	0.3316
0.3293	0.3461	0.3373	0.3534	0.3293	0.3384
0.3292	0.3539	0.3376	0.3616	0.3293	0.3461
1	B3	В	4	В	5
CIE x	CIE y	CIE x	CIE y	CIE x	CIE y
0.3293	0.3461	0.3217	0.3316	0.3293	0.3384
0.3293	0.3384	0.3222	0.3243	0.3294	0.3306
0.3369	0.3451	0.3294	0.3306	0.3366	0.3369
0.3373	0.3534	0.3293	0.3384	0.3369	0.3451
(C0	С	1	С	2
CIE x	CIE y	CIE x	CIE y	C CIE x	2 CIE y
CIE x	CIE y	CIE x	CIE y	CIE x	CIE y
CIE x 0.3376	CIE y 0.3616	CIE x 0.3463	CIE y 0.3687	CIE x 0.3373	CIE y 0.3534
CIE x 0.3376 0.3373	CIE y 0.3616 0.3534	CIE x 0.3463 0.3456	CIE y 0.3687 0.3601	CIE x 0.3373 0.3369	CIE y 0.3534 0.3451
CIE x 0.3376 0.3373 0.3456 0.3463	OIE y 0.3616 0.3534 0.3601	CIE x 0.3463 0.3456 0.3539 0.3552	CIE y 0.3687 0.3601 0.3669	CIE x 0.3373 0.3369 0.3448	CIE y 0.3534 0.3451 0.3514 0.3601
CIE x 0.3376 0.3373 0.3456 0.3463	CIE y 0.3616 0.3534 0.3601 0.3687	CIE x 0.3463 0.3456 0.3539 0.3552	OIE y 0.3687 0.3601 0.3669 0.3760	CIE x 0.3373 0.3369 0.3448 0.3456	CIE y 0.3534 0.3451 0.3514 0.3601
OIE x 0.3376 0.3373 0.3456 0.3463	CIE y 0.3616 0.3534 0.3601 0.3687	CIE x 0.3463 0.3456 0.3539 0.3552	CIE y 0.3687 0.3601 0.3669 0.3760	CIE x 0.3373 0.3369 0.3448 0.3456	CIE y 0.3534 0.3451 0.3514 0.3601
CIE x 0.3376 0.3373 0.3456 0.3463	CIE y 0.3616 0.3534 0.3601 0.3687 C3 CIE y	CIE x 0.3463 0.3456 0.3539 0.3552 CIE x	OIE y 0.3687 0.3601 0.3669 0.3760	CIE x 0.3373 0.3369 0.3448 0.3456 CIE x	CIE y 0.3534 0.3451 0.3514 0.3601 5 CIE y
OIE x 0.3376 0.3373 0.3456 0.3463 CIE x 0.3456	OIE y 0.3616 0.3534 0.3601 0.3687 C3 CIE y 0.3601	CIE x 0.3463 0.3456 0.3539 0.3552 CIE x 0.3369	CIE y 0.3687 0.3601 0.3669 0.3760 4 CIE y 0.3451	CIE x 0.3373 0.3369 0.3448 0.3456 CIE x 0.3448	CIE y 0.3534 0.3451 0.3514 0.3601 5 CIE y 0.3514

Color Bin Structure

CIE Chromaticity Diagram, $T_i=25\,^{\circ}$ C, $I_F=1\,^{\circ}$ A

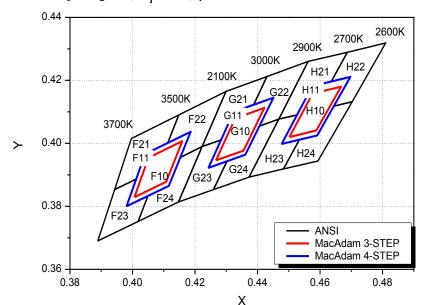


	3-S	TEP			4-S1	ΓEP	
D.	10	E.	10	D11 E11		11	
CIE x	CIE y	CIE x	CIE y	CIE x	CIE y	CIE x	CIE y
0.3589	0.3685	0.3764	0.3713	0.3560	0.3557	0.3746	0.3689
0.3665	0.3742	0.3793	0.3828	0.3580	0.3697	0.3784	0.3841
0.3637	0.3622	0.3890	0.3887	0.3681	0.3771	0.3914	0.3922
0.3573	0.3579	0.3854	0.3768	0.3645	0.3618	0.3865	0.3762

			AN	ISI			
D	21	D	22	D	23	D	24
CIE x	CIE y						
0.3528	0.3599	0.3628	0.3732	0.3601	0.3587	0.3511	0.3466
0.3548	0.3736	0.3641	0.3805	0.3645	0.3618	0.3528	0.3599
0.3641	0.3805	0.3736	0.3874	0.3663	0.3699	0.3570	0.3631
0.3628	0.3732	0.3703	0.3728	0.3703	0.3728	0.3560	0.3558
0.3580	0.3697	0.3663	0.3699	0.3670	0.3578	0.3601	0.3587
0.3570	0.3631	0.3681	0.3771	0.3590	0.3521	0.3590	0.3521
E	21	E	22	E:	23	E	24
CIE x	CIE y						
0.3703	0.3726	0.3890	0.3842	0.3670	0.3578	0.3784	0.3647
0.3736	0.3874	0.3914	0.3922	0.3703	0.3726	0.3806	0.3725
0.3871	0.3959	0.3849	0.3881	0.3765	0.3765	0.3865	0.3762
0.3849	0.3881	0.3871	0.3959	0.3746	0.3689	0.3890	0.3842
0.3784	0.3841	0.4006	0.4044	0.3806	0.3725	0.3952	0.3880
0.3765	0.3765	0.3952	0.3880	0.3784	0.3647	0.3898	0.3716

Color Bin Structure

CIE Chromaticity Diagram, $T_i=25\,^{\circ}$, $I_F=1A$



						/ \					
3-STEP						4-STEP					
F'	10	G	10	H	10	F'	11	G	11	H	11
CIE x	CIE y										
0.4006	0.3829	0.4267	0.3946	0.4502	0.4020	0.3981	0.3800	0.4243	0.3922	0.4477	0.3998
0.4051	0.3954	0.4328	0.4079	0.4576	0.4158	0.4040	0.3966	0.4324	0.4100	0.4575	0.4182
0.4159	0.4007	0.4422	0.4113	0.4667	0.4180	0.4186	0.4037	0.4451	0.4145	0.4697	0.4211
0.4108	0.3878	0.4355	0.3977	0.4588	0.4041	0.4116	0.3865	0.4361	0.3964	0.4591	0.4025

0.4108	0.3878	0.4355	0.3977	0.4588	0.4041	0.4116	0.3865	0.4361	0.3964	0.4591	0.4025	
	ANSI											
	F21			F22			F23			F24		
CIE x		CIE y										
0.4148	в (0.4090	0.4013	3 (0.3887	0.4223	3 (0.3990	0.4299	9	0.4165	
0.3996	6 (0.4015	0.3943	3 (0.3853	0.4153	3 (0.3955	0.4148	3	0.4090	
0.3943	3 ().3853	0.3889	9 (0.3690	0.4116	6 (0.3865	0.4113	3	0.4002	
0.4013	3 ().3887	0.4018	3 (0.3752	0.4049) (0.3833	0.418	3	0.4037	
0.4040	0 0	0.3966	0.4049	9 (0.3833	0.4018	3 (0.3752	0.415	3	0.3955	
0.4113	3 (0.4002	0.398	1 (0.3800	0.4147	7 (0.3814	0.4223	3	0.3990	
	G21			G22			G23			G24		
CIE x	[CIE y	CIE x		CIE y	CIE x		CIE y	CIE x	•	CIE y	
0.4223	3 (0.3990	0.4406	6 (0.4055	0.4147	7 (0.3814	0.4259	9	0.3853	
0.4299	9 ().4165	0.445	1 ().4145	0.4223	3 (0.3990	0.4302	2	0.3943	
0.4430	0 0).4212	0.4387	7 ().4122	0.4284	1 (0.4011	0.436	1	0.3964	
0.4387	7 ().4122	0.4430) ().4212	0.4243	3 (0.3922	0.440	6	0.4055	
0.4324	4 (0.4100	0.4562	2 (0.4260	0.4302	2 (0.3943	0.4468	3	0.4077	
0.4284	4 (0.4011	0.4468	3 (0.4077	0.4259) (0.3853	0.437	3	0.3893	
	H21			H22			H23			H24		
CIE x	:	CIE y	CIE x		CIE y	CIE x		CIE y	CIE x	:	CIE y	
0.4468	8 (0.4077	0.464	4 (0.4118	0.4373	3 (0.3893	0.4483	3	0.3919	
0.4562	2 (0.4260	0.4697	7 ().4211	0.4468	3 (0.4077	0.453	4	0.4012	
0.468	7 ().4289	0.4636	6 (0.4197	0.4526	6 (0.4090	0.459	1	0.4025	
0.4636	6 ().4197	0.4687	7 (0.4289	0.4477	7 (0.3998	0.464	4	0.4118	
0.457	5 ().4182	0.4810) (0.4319	0.4534	1 (0.4012	0.4703	3	0.4132	
0.4526	6 (0.4090	0.4703	3 (0.4132	0.4483	3 (0.3919	0.4593	3	0.3944	

Color Bin Structure

Table 7. Bin Code description

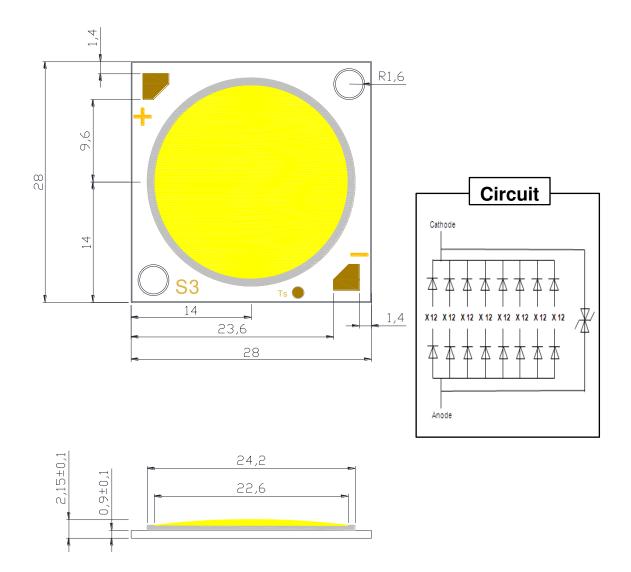
Part Number	Luminous Flux (lm) @ l _F = 1A			Color Chromaticity Coordinate	Typical Forward Voltage (V₁) @I _F = 1A		
	Bin Code	Min.	Max.	@ I _F = 1A	Bin Code	Min.	Max.
	K1	3900	4500		D	32.0	34.0
SDW05F1C	K2	4500	5100	Refer to page.15~17	E	34.0	38.0
	L1	5100	5800		F	38.0	40.0
	J2	3400	3900		D	32.0	34.0
SDW85F1C	K1	3900	4500	Refer to page.15~18	E	34.0	38.0
	K2	4500	5100		F	38.0	40.0
	J1	2900	3400	Defeate	D	32.0	34.0
SDW95F1C	J2	3400	3900	Refer to page.15~18	E	34.0	38.0
	K1	3900	4500		F	38.0	40.0

Table 8. Ordering Information(Bin Code)

Available ranks

Part Number	сст	CIE	LF rank			VF rank		
SDW05F1C -	5300~6000K	В	K1	K2	L1	D	Е	F
	4700~5300K	С	K1	K2	L1	D	Е	F
	4200~4700K	D	K1	K2	L1	D	E	F
	3700~4200K	Е	K1	K2	L1	D	Е	F
SDW85F1C -	5300~6000K	В	J2	K1	K2	D	E	F
	4700~5300K	С	J2	K1	K2	D	Е	F
	3700~4200K	Е	J2	K1	K2	D	Е	F
	3200~3700K	F	J2	K1	K2	D	E	F
	2900~3700K	G	J2	K1	K2	D	Е	F
	2600~2900K	Н	J2	K1	K2	D	Е	F
SDW95F1C -	3700~4200K	Е	J1	J2	K1	D	Е	F
	3200~3700K	F	J1	J2	K1	D	E	F
	2900~3700K	G	J1	J2	K1	D	E	F
	2600~2900K	Н	J1	J2	K1	D	E	F

Mechanical Dimensions



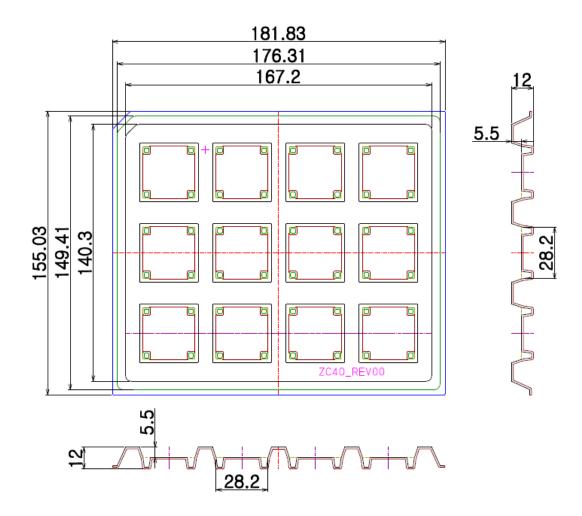
Notes:

(1) All dimensions are in millimeters.

(2) Scale: none

(3) Undefined tolerance is $\pm 0.2 mm$

Packaging Specification



Notes:

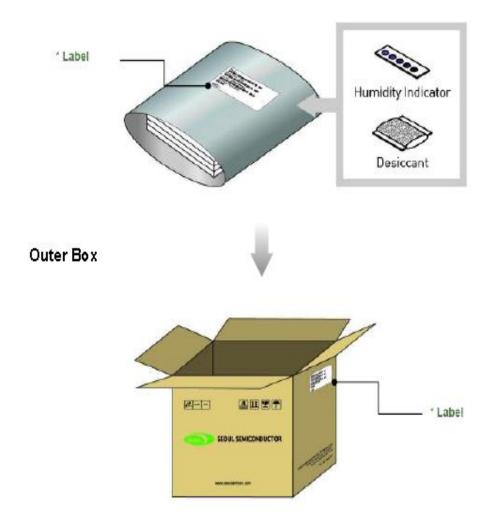
(1) Quantity: 12pcs/Tray

(2) All dimensions are in millimeters (tolerance : $\pm 0.3)\,$

(3) Scale none

Packaging Specification

Aluminum Bag



Notes:

- (1) Heat Sealed after packing (Use Zipper Bag)
- (2) Quantity: 3Tray(36pcs)/Bag

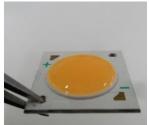
Handling of Silicone Resin for LEDs

(1) During processing, mechanical stress on the surface should be minimized as much as possible. Sharp objects of all types should not be used to pierce the sealing compound.



(2) In general, LEDs should only be handled from the side. By the way, this also applies to LEDs without a silicone sealant, since the surface can also become scratched.





- (3) Silicone differs from materials conventionally used for the manufacturing of LEDs. These conditions must be considered during the handling of such devices. Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust. As mentioned previously, the increased sensitivity to dust requires special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of wire.
- (4) Seoul Semiconductor suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the LED.
- (5) Please do not mold this product into another resin (epoxy, urethane, etc) and do not handle this product with acid or sulfur material in sealed space.
- (6) Avoid leaving fingerprints on silicone resin parts.

Precaution for Use

(1) Storage

To avoid the moisture penetration, we recommend storing Power LEDs in a dry box with a desiccant.

The recommended storage temperature range is 5° C to 30° C and a maximum humidity of 50%.

- (2) Use Precaution after Opening the Packaging. Pay attention to the following:
 - a. Recommend conditions after opening the package
 - Sealing
 - Temperature : 5 ~ 40 °C Humidity : less than RH30%
 - b. If the package has been opened more than 4 week or the color of the desiccant changes.
- (3) For manual soldering

Seoul Semiconductor recommends the soldering condition

(ZC series product is not adaptable to reflow process)

- a. Use lead-free soldering
- b. Soldering should be implemented using a soldering equipment at temperature lower than 350°C.
- c. Before proceeding the next step, product temperature must be stabilized at room temperature.
- (4) Components should not be mounted on warped (non coplanar) portion of PCB.
- (5) Radioactive exposure is not considered for the products listed here in.
- (6) It is dangerous to drink the liquid or inhale the gas generated by such products when chemically disposed of.
- (7) This device should not be used in any type of fluid such as water, oil, organic solvent and etc. When washing is required, IPA (Isopropyl Alcohol) should be used.
- (8) When the LEDs are in operation the maximum current should be decided after measuring the package temperature.
- (9) LEDs must be stored properly to maintain the device. If the LEDs are stored for 3 months or more after being shipped from Seoul Semiconductor, a sealed container with vacuum atmosphere should be used for storage.
- (10) The appearance and specifications of the product may be modified for improvement without notice.

Precaution for Use

- (11) Long time exposure of sun light or occasional UV exposure will cause silicone discoloration.
- (12) Attaching LEDs, do not use adhesive that outgas organic vapor.
- (13) The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration can be generated resulting in LED damage.
- (14) Please do not touch any of the circuit board, components or terminals with bare hands or metal while circuit is electrically active.
- (15) VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can penetrate silicone encapsulants of LEDs and discolor when exposed to heat and photonic energy. The result can be a significant loss of light output from the fixture. Knowledge of the properties of the materials selected to be used in the construction of fixtures can help prevent these issues.
- (16) LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS). Below is a list of suggestions that Seoul Semiconductor purposes to minimize these effects.
- I. ESD (Electro Static Discharge)

Electrostatic discharge (ESD) is the defined as the release of static electricity when two objects come into contact. While most ESD events are considered harmless, it can be an expensive problem in many industrial environments during production and storage. The damage from ESD to an LEDs may cause the product to demonstrate unusual characteristics such as:

- Increase in reverse leakage current lowered turn-on voltage
- Abnormal emissions from the LED at low current

The following recommendations are suggested to help minimize the potential for an ESD event. One or more recommended work area suggestions:

- Ionizing fan setup
- ESD table/shelf mat made of conductive materials
- ESD safe storage containers

One or more personnel suggestion options:

- Antistatic wrist-strap
- Antistatic material shoes
- Antistatic clothes

Environmental controls:

- Humidity control (ESD gets worse in a dry environment)